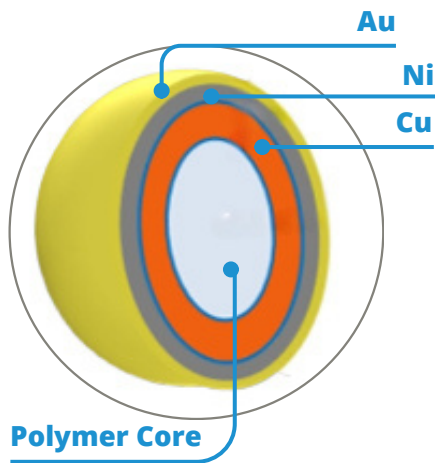


DATA SHEET POLYMER CORE SOLDER BALLS

### General informations

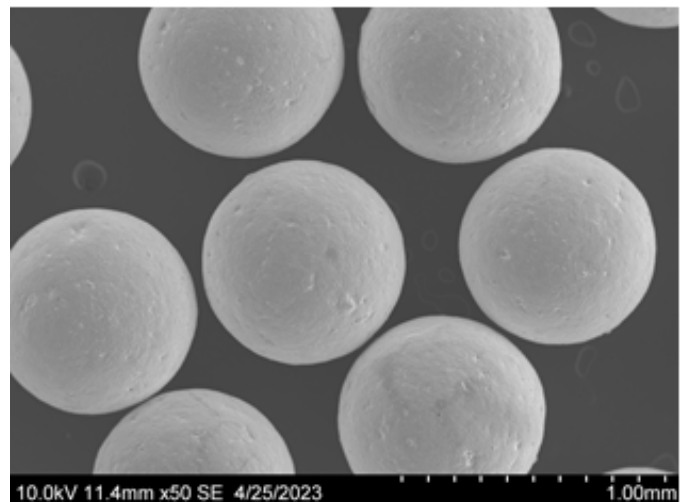


- Alternative to traditional non-collapsible lead solder balls
- Minimize mechanical stress
- Improve reliability and reparability
- Compatible with solder reflow according to IPC-J-STD-001
- Miniaturisation
- Flexible design w/ different possible coating
- Excellent corrosion resistance with extended shelf life (up to 1 year)
- Can be mounted using ICA or solder paste (lead free compatible)
- Controlled stand-off height (+/-5%)

Polymer core solder balls help improving the lifespan of electrical contact for assembling BGAs on a printed circuit board

### Technical Data

Reference	PCSB_500_Au
Ball size	500 µm +/- 5%
Coating design* :	Cu Ni Au
from 50 nm to 20 um	
Ball weight	~ 0.147g / 1000 balls



\*Other possible configurations on demand